

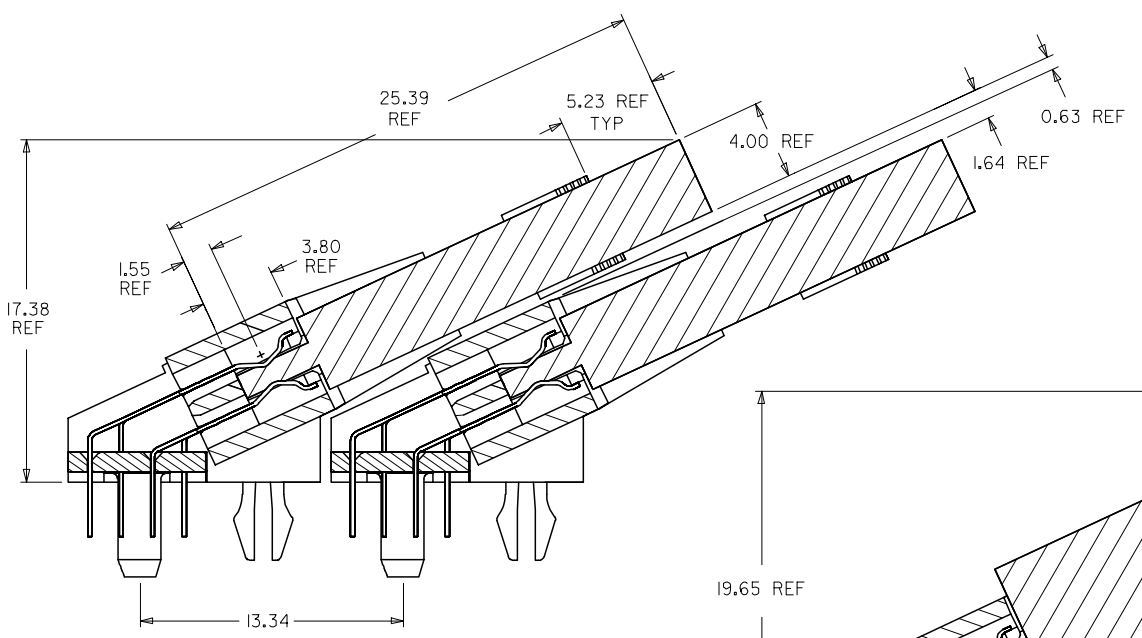
NOTES:

- MATERIALS:** HOUSING, BASEPLATE AND LATCH - HIGH TEMPERATURE THERMOPLASTIC, UL 94-V0
TERMINAL AND FORKLOCK - COPPER ALLOY
- FINISHES:** CONTACT AREA: SEE TABLE ON SHEET 4
SOLDER TAILS: 2.54µm/100µ" MIN. TIN/LEAD OR TIN OVER 1.27µm/50µ" MIN. NICKEL
- PRODUCT SPECIFICATIONS:** PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
- DATE CODE** SHALL BE MARKED LEGIBLY AS SHOWN: XX XX YEAR WEEK
- PART NUMBER** SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX REFER TO TABLE

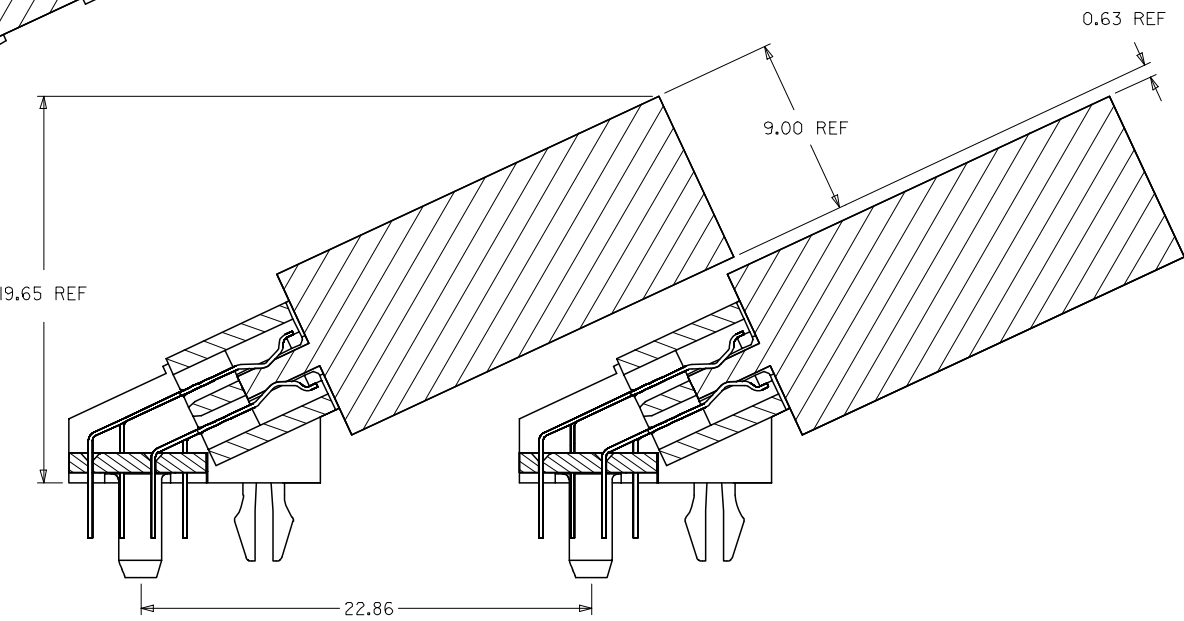
ADD NEW PART NO EC NO: S2005-0439 2004/12/30 DRAWN: SHLENI CHKD: RAMESH APPR: GGLEE 2004/12/30	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5°	DRAWN BY LPL IM	DATE 2000/01/10
B1	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED	
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		MATERIAL NO.	DOCUMENT NO. SD-87623-001	SHEET NO. 1 OF 4

10 9 8 7 6 5 4 3 2 1

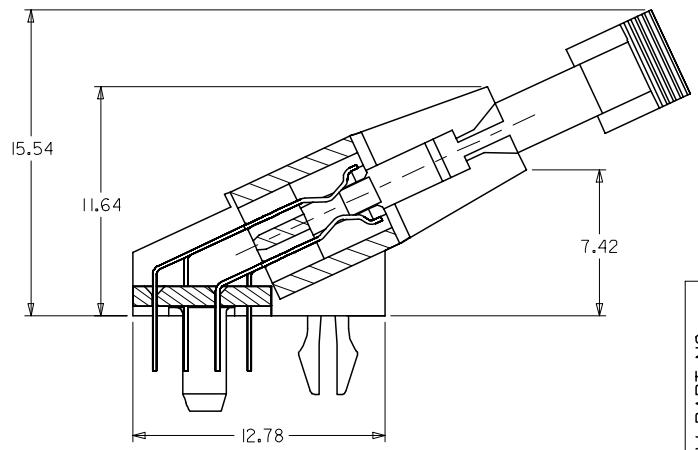
F
E
D
C
B
A



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00 mm THICK
MODULE (TYPICAL TSOP PACKAGING)



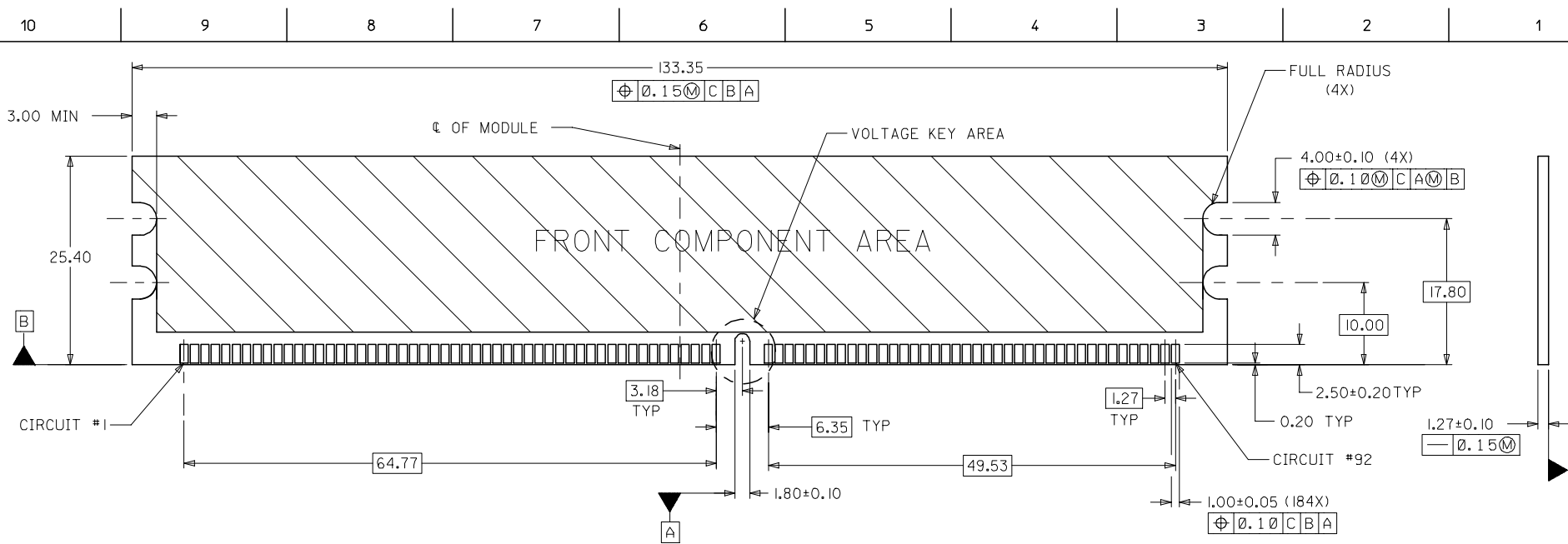
MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00 mm THICK
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

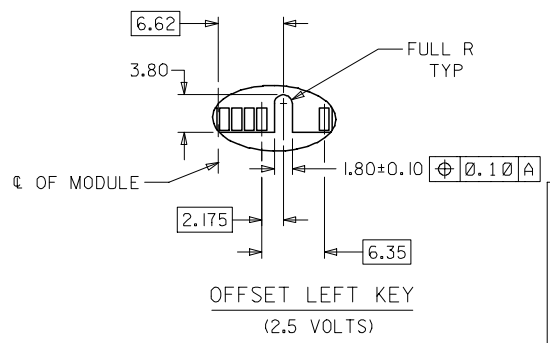
ADD NEW PART NO EC NO: S2005-0439 2004/12/30 DRAWN: SHLENI 2004/12/30 CHKD: RAMESH 2004/12/30 APPR: GGLEE 2004/12/30	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.			
		4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2000/02/02				
		3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED			
2 PLACES	± 0.25	± ---	MATERIAL NO.	DOCUMENT NO. SD-87623-001	SHEET NO. 2 OF 4					
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR ± 5 °		SEE TABLE								

9 8 7 6 5 4 3 2 1



RECOMMENDED MODULE LAYOUT
 (PER JEDEC STANDARD MO-206, 184 CKT.)
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

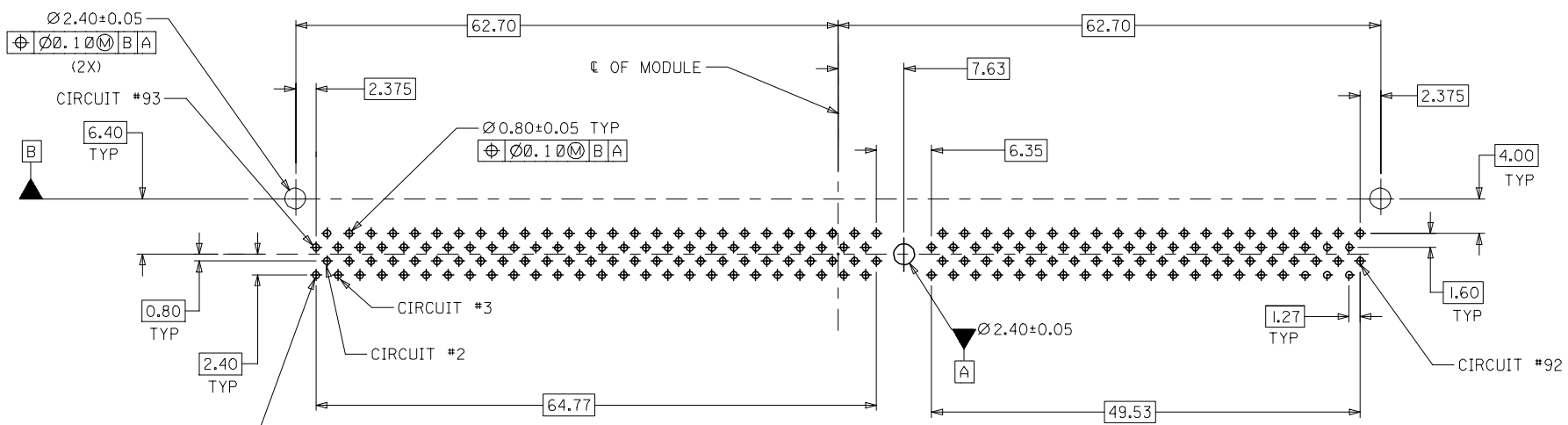
VOLTAGE KEY AREA



ADD NEW PART NO EC NO: S2005-0439 DRAWN: SHLENI 2004/12/30 CHKD: RAMESH 2004/12/30 APPR: GGLEE 2004/12/30	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED	DOCUMENT NO. SD-87623-001	SHEET NO. 3 OF 4
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

PLATING OPTION	ASSEMBLY PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH Q±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
TIN/LEAD	87623-0001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
	87623-0011			3.18	4.83	3.94		
	87623-0012			3.18	3.18	3.18		
	87623-0013			3.81	4.83	4.42	2.84	
	87623-0101			2.79	3.18	3.18	1.57	
	87623-0111			3.18	4.83	3.94		
	87623-0113			3.81	4.83	4.42		
87623-0115	3.18	3.18	3.18	1.57				
TIN	87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
	87623-2011			3.18	4.83	3.94		
	87623-2012			3.18	3.18	3.18		
	87623-2013			3.81	4.83	4.42	2.84	
	87623-2101			2.79	3.18	3.18	1.57	
	87623-2111			3.18	4.83	3.94		
	87623-2113			3.81	4.83	4.42		
	87623-2115			3.18	3.18	3.18	1.57	



RECOMMENDED
P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

ADD NEW PART NO EC NO: S2005-0439 DRAWN: SHLENI 2004/12/30 CHKD: RAMESH 2004/12/30 APPR: GGLEE 2004/12/30 REV B1	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY LPL IM 2000/01/10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		APPROVED BY SKTOH 2000/02/02	DATE 2000/02/02	MOLEX INCORPORATED	
				MATERIAL NO.	DOCUMENT NO. SD-87623-001	SHEET NO. 4 OF 4	

9 8 7 6 5 4 3 2 1